

### 1. Shock & Drop • Vibration

Do not inflict excessive shock and mechanical vibration that exceeds the norm, such as hitting or mistakenly dropping, when transporting and mounting on a board. There are cases when pieces of crystal break, and pieces that are used become damaged, and become inoperable. When a shock or vibration that exceeds the norm has been inflicted, make sure to check the characteristics.

### 2. Cleaning

Since a crystal piece can be broken by resonance when a crystal device is cleaned by ultrasonic cleaning, be careful when carrying out ultrasonic cleaning.

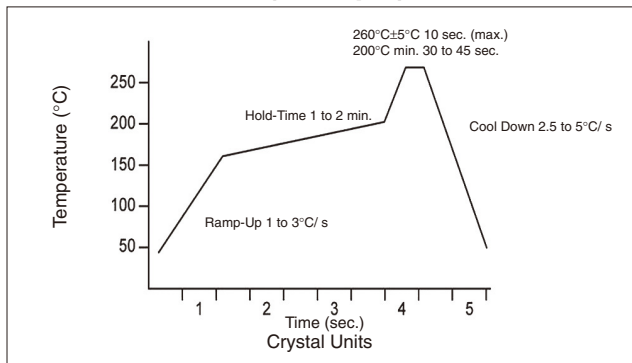
### 3. Soldering conditions

To maintain the product reliability, please follow recommended conditions.

#### Standard soldering iron conditions

	Crystal Units
Soldering iron	280°C to 340°C
Time	3+1/ -0 sec. max.

#### Reflow conditions (Example)



Recommended reflow Conditions vary depending upon products. Please check with the respective specification for details.

### 4. Mounting Precautions

#### Leaded Devices

The special glass, located where the lead of the retainer base comes out, is aligned with the coefficient of thermal expansion of the lead, if the glass is damaged and cracks appear, there may be cases in which performance deteriorates and it fails to operate.

Consequently, when making the device adhere closely and applying solder, align the gap of the hole of the board with the gap of the lead and insert without excessive force.

When making the device adhere closely to a through hole board and applying solder, be careful that the solder does not get into the metal part of the retainer base and cause a short. Putting in an insulation spacer is one more method of preventing a short circuit.

When the lead is mounted floating, fix it as far as possible so that contact with other parts and the breakage due to the fatigue, and the mechanical resonance of the lead will not occur.

When the lead is bent and used, do not bend the lead directly from the base, separate it 0.5mm or more and then bend it. When bending, before attaching to the board, fix the place where the lead comes out in advance and attach it after bending so that a crack does not occur in the glass part.

#### Surface Mount Devices

The lead of the device and the pattern of the board is soldered on the surface. Since extreme deformation of the board tears off the pattern, tears off the lead metal, cracks the solder and damages the sealed part of the device and there are cases in which performance deteriorates and operation fails, use it within the stipulated bending conditions. Due to the small cracks in the board resulting from mounting, please pay sufficient attention when attaching a device at the position where the warping of the board is great.

When using an automatic loading machine, as far as possible, select a type that has a small impact and use it while confirming that there is no damage.

Surface mount devices are NOT flow soldering compatible.

### 5. Storage Condition

Since the long hour high temperature and low temperature storage, as well as the storage at high humidity are causes of deterioration in frequency accuracy and solderability.

Parts should be stored in temperature range of -5 to +40°C, humidity 40 to 60% RH, and avoid direct sunlight. Then use within 6 months.